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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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HD74HC251

1 of 8 Data Selectors/Multiplexers (with 3-state outputs)



ADE-205-476 (Z)
1st. Edition
Sep. 2000

Description

This multiplexer features both true (Y) and complement (W) outputs as well as a strobe input. The strobe must be at a low logic level to enable this device. When the strobe input is high, both outputs are in the high impedance state. When enabled, address information on the data select inputs determines which data input is routed to the Y and W outputs.

Features

- High Speed Operation: t_{pd} (A, B, C to Y) = 20 ns typ ($C_L = 50$ pF)
- High Output Current: Fanout of 10 LSTTL Loads
- Wide Operating Voltage: $V_{CC} = 2$ to 6 V
- Low Input Current: 1 μ A max
- Low Quiescent Supply Current: I_{CC} (static) = 4 μ A max ($T_a = 25^\circ\text{C}$)

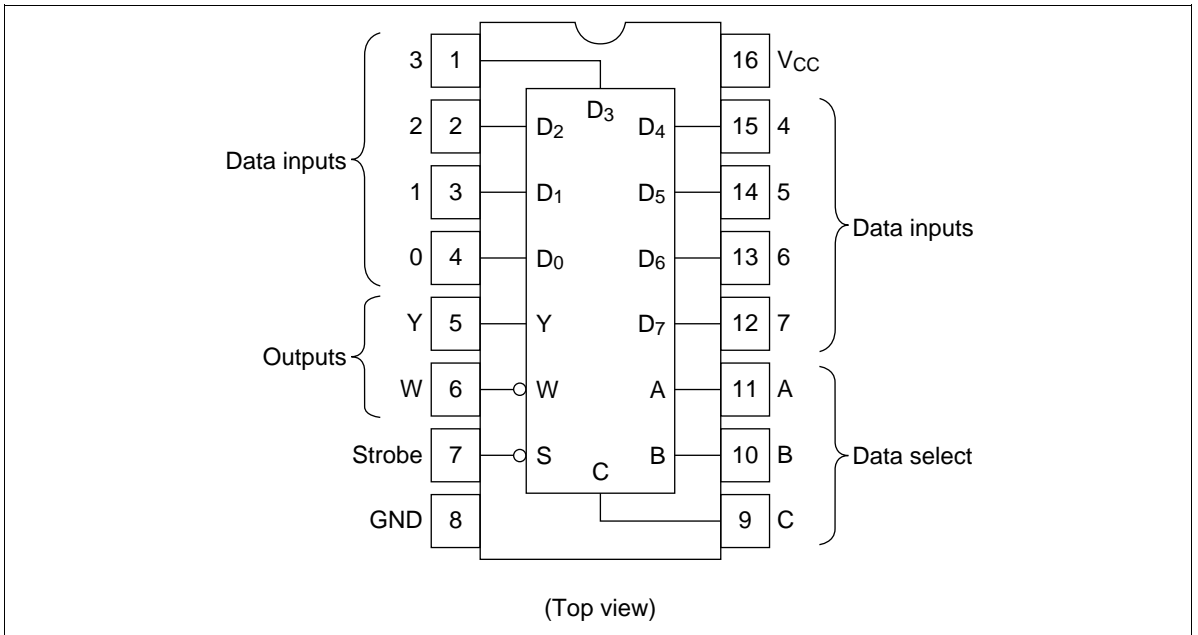
Function Table

Inputs

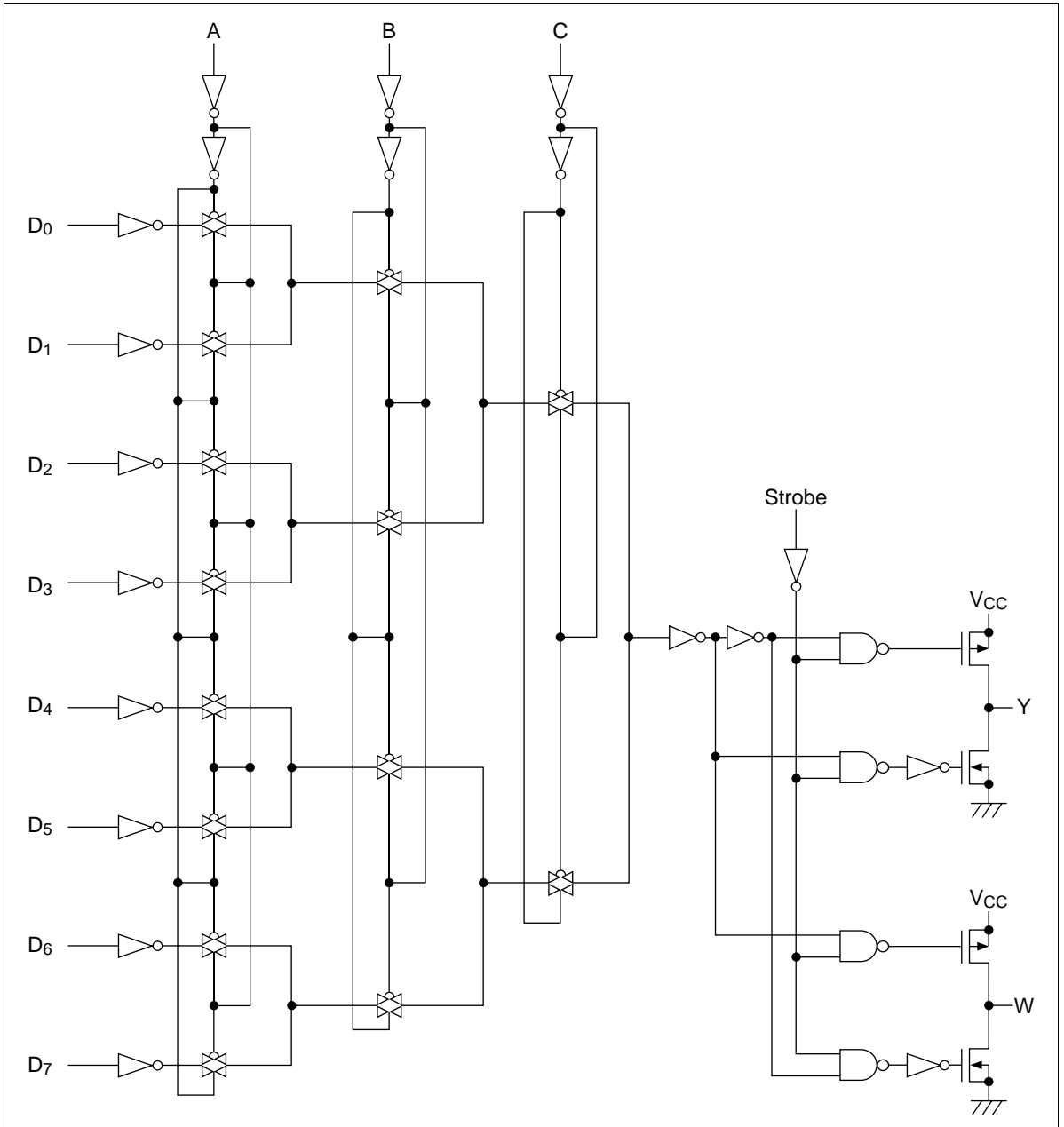
Select			Strobe	Outputs	
C	B	A	S	Y	W
X	X	X	H	Z	Z
L	L	L	L	D ₀	\overline{D}_0
L	L	H	L	D ₁	\overline{D}_1
L	H	L	L	D ₂	\overline{D}_2
L	H	H	L	D ₃	\overline{D}_3
H	L	L	L	D ₄	\overline{D}_4
H	L	H	L	D ₅	\overline{D}_5
H	H	L	L	D ₆	\overline{D}_6
H	H	H	L	D ₇	\overline{D}_7

- Notes
1. H: high level, L: low level, X: irrelevant
 2. Z: high impedance (off-state)
 3. D₀ through D₇; the level of the respective D input.

Pin Arrangement



Block Diagram



DC Characteristics

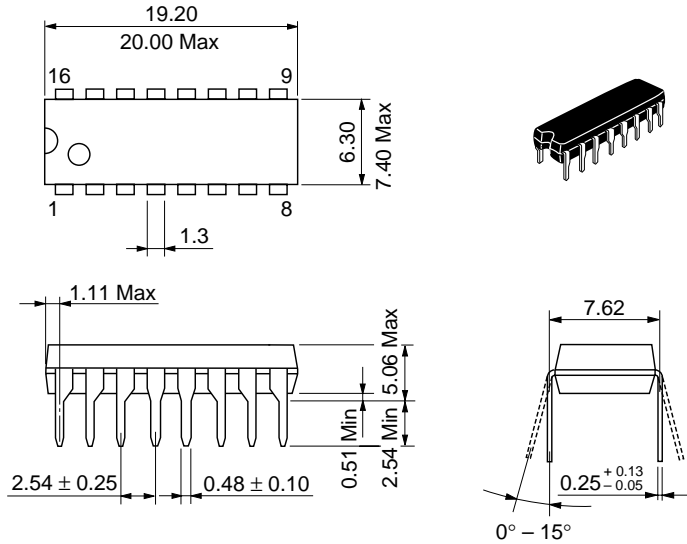
Item	Symbol	V _{CC} (V)	Ta = 25°C		Ta = -40 to +85°C		Unit	Test Conditions		
			Min	Typ	Max	Min			Max	
Input voltage	V _{IH}	2.0	1.5	—	—	1.5	—	V		
		4.5	3.15	—	—	3.15	—			
		6.0	4.2	—	—	4.2	—			
	V _{IL}	2.0	—	—	0.5	—	0.5		V	
		4.5	—	—	1.35	—	1.35			
		6.0	—	—	1.8	—	1.8			
Output voltage	V _{OH}	2.0	1.9	2.0	—	1.9	—	V		Vin = V _{IH} or V _{IL} I _{OH} = -20 μA
		4.5	4.4	4.5	—	4.4	—			
		6.0	5.9	6.0	—	5.9	—			
		4.5	4.18	—	—	4.13	—		I _{OH} = -4 mA	
		6.0	5.68	—	—	5.63	—		I _{OH} = -5.2 mA	
	V _{OL}	2.0	—	0.0	0.1	—	0.1	V	Vin = V _{IH} or V _{IL} I _{OL} = 20 μA	
		4.5	—	0.0	0.1	—	0.1			
		6.0	—	0.0	0.1	—	0.1			
		4.5	—	—	0.26	—	0.33			I _{OL} = 4 mA
		6.0	—	—	0.26	—	0.33			I _{OL} = 5.2 mA
Off-state output current	I _{OZ}	6.0	—	—	±0.5	—	±5.0	μA	Vin = V _{IH} or V _{IL} , Vout = V _{CC} or GND	
Input current	I _{in}	6.0	—	—	±0.1	—	±1.0	μA	Vin = V _{CC} or GND	
Quiescent supply current	I _{CC}	6.0	—	—	4.0	—	40	μA	Vin = V _{CC} or GND, Iout = 0 μA	

AC Characteristics ($C_L = 50$ pF, Input $t_r = t_f = 6$ ns)

Item	Symbol	V_{CC} (V)	$T_a = 25^\circ\text{C}$		$T_a = -40$ to $+85^\circ\text{C}$		Unit	Test Conditions		
			Min	Typ	Max	Min			Max	
Propagation delay time	t_{PLH}	2.0	—	—	205	—	255	ns	A, B or C to Y	
		4.5	—	20	41	—	51			
		6.0	—	—	35	—	43			
	t_{PHL}	2.0	—	—	205	—	255	ns	A, B or C to W	
		4.5	—	20	41	—	51			
		6.0	—	—	35	—	43			
	t_{PLH}	2.0	—	—	195	—	245	ns	Data to Y	
		4.5	—	17	39	—	49			
		6.0	—	—	33	—	42			
	t_{PHL}	2.0	—	—	185	—	230	ns	Data to W	
		4.5	—	17	37	—	46			
		6.0	—	—	31	—	39			
	Output enable time	t_{ZH}	2.0	—	—	150	—	190	ns	strobe to W $R_L = 1$ k Ω
			4.5	—	11	30	—	38		
			6.0	—	—	26	—	33		
		t_{ZL}	2.0	—	—	145	—	180	ns	strobe to Y $R_L = 1$ k Ω
			4.5	—	11	29	—	36		
			6.0	—	—	25	—	31		
Output disable time	t_{HZ}	2.0	—	—	220	—	275	ns	strobe to W $R_L = 1$ k Ω	
		4.5	—	12	44	—	55			
		6.0	—	—	37	—	47			
	t_{LZ}	2.0	—	—	195	—	245	ns	strobe to Y $R_L = 1$ k Ω	
		4.5	—	12	39	—	49			
		6.0	—	—	33	—	42			
Output rise/fall time	t_{TLH}	2.0	—	—	75	—	90	ns		
	t_{THL}	4.5	—	5	15	—	19			
	t_{THL}	6.0	—	—	13	—	16			
Input capacitance	C_{in}	—	—	5	10	—	10	pF		

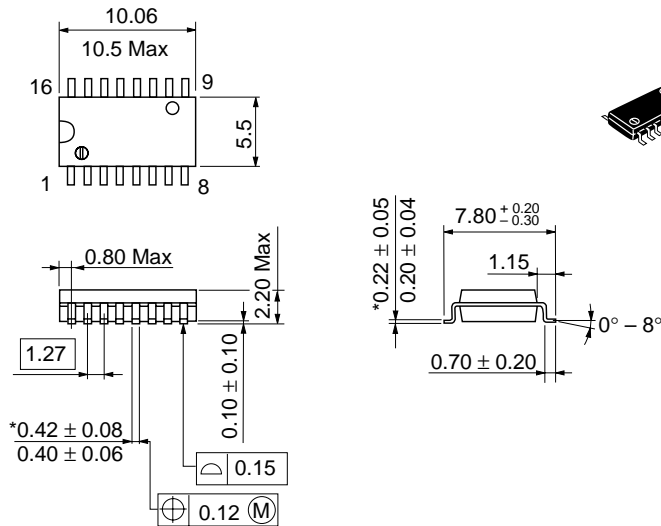
Package Dimensions

Unit: mm



Hitachi Code	DP-16
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	1.07 g

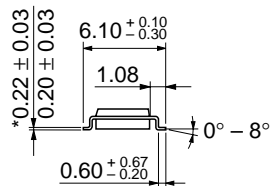
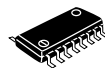
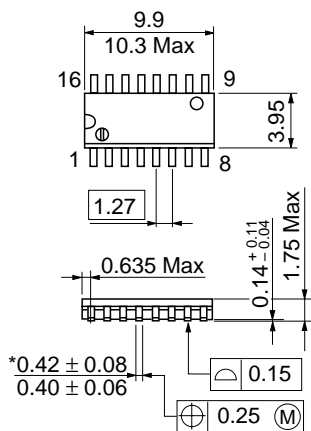
Unit: mm



Hitachi Code	FP-16DA
JEDEC	—
EIAJ	Conforms
Mass (reference value)	0.24 g

*Dimension including the plating thickness
Base material dimension

Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-16DN
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	0.15 g

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HITACHI

Hitachi, Ltd.

Semiconductor & Integrated Circuits.

Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan
Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

URL NorthAmerica : <http://semiconductor.hitachi.com/>
 Europe : <http://www.hitachi-eu.com/hel/ecg>
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For further information write to:

Hitachi Semiconductor
(America) Inc.
179 East Tasman Drive,
San Jose, CA 95134
Tel: <1> (408) 433-1990
Fax: <1> (408) 433-0223

Hitachi Europe GmbH
Electronic Components Group
Dornacher Straße 3
D-85622 Feldkirchen, Munich
Germany
Tel: <49> (89) 9 9180-0
Fax: <49> (89) 9 29 30 00

Hitachi Europe Ltd.
Electronic Components Group.
Whitebrook Park
Lower Cookham Road
Maidenhead
Berkshire SL6 8YA, United Kingdom
Tel: <44> (1628) 585000
Fax: <44> (1628) 585160

Hitachi Asia Ltd.
Hitachi Tower
16 Collyer Quay #20-00,
Singapore 049318
Tel : <65>-538-6533/538-8577
Fax : <65>-538-6933/538-3877
URL : <http://www.hitachi.com.sg>

Hitachi Asia Ltd.
(Taipei Branch Office)
4/F, No. 167, Tun Hwa North Road,
Hung-Kuo Building,
Taipei (105), Taiwan
Tel : <886>-(2)-2718-3666
Fax : <886>-(2)-2718-8180
Telex : 23222 HAS-TP
URL : <http://www.hitachi.com.tw>

Hitachi Asia (Hong Kong) Ltd.
Group III (Electronic Components)
7/F., North Tower,
World Finance Centre,
Harbour City, Canton Road
Tsim Sha Tsui, Kowloon,
Hong Kong
Tel : <852>-(2)-735-9218
Fax : <852>-(2)-730-0281
URL : <http://www.hitachi.com.hk>

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